

放熱接着剤

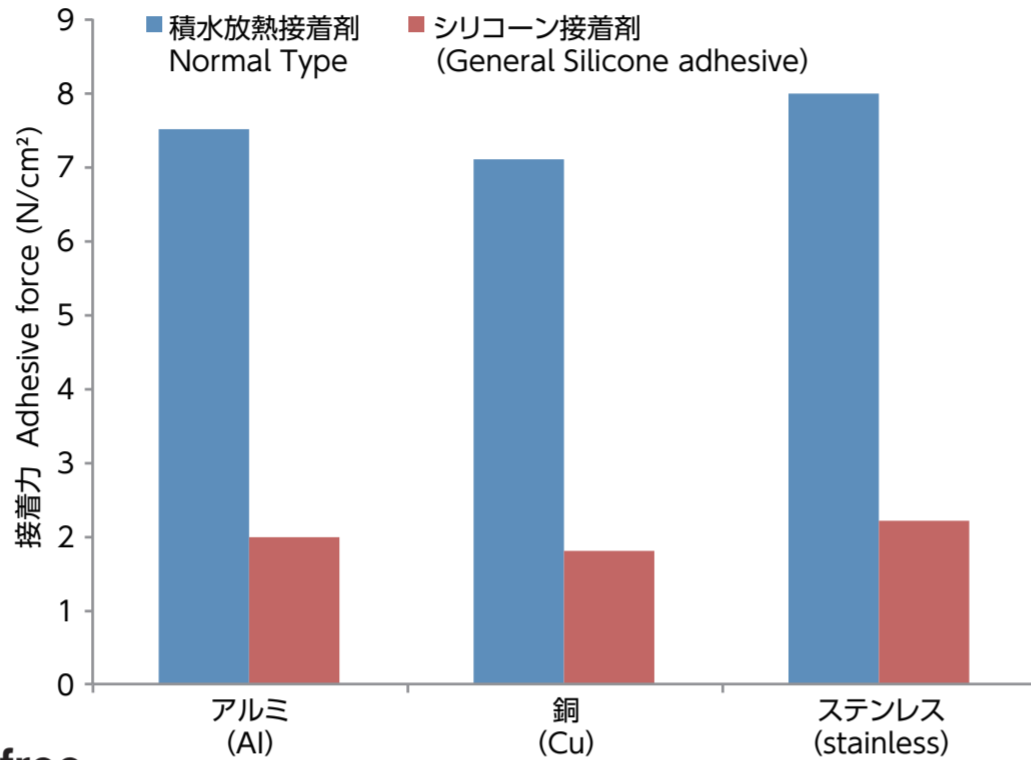
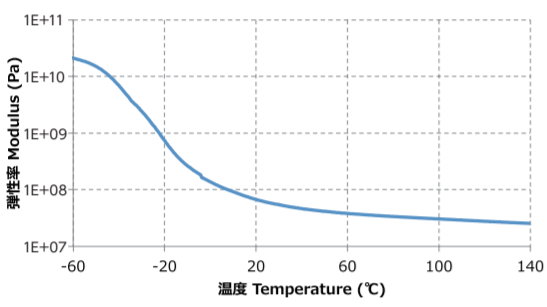
Heat Release Adhesives (Epoxy)

1液熱硬化放熱接着剤 Single Component Heat Curable Heat Release Adhesive

特徴 Features

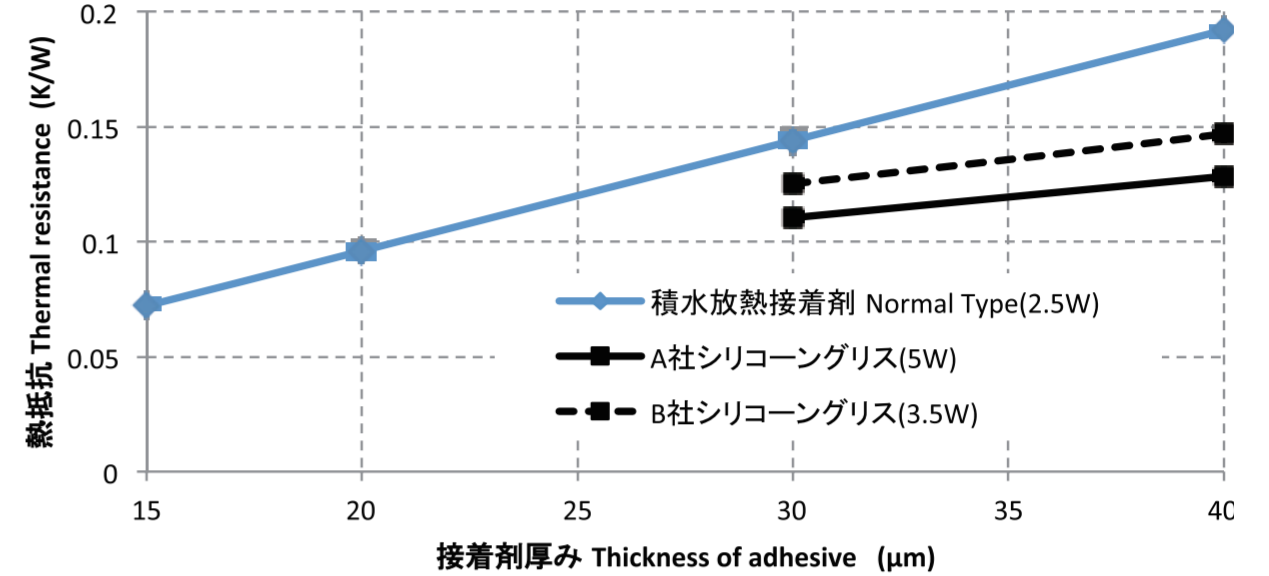
★低弾性と接着性を両立

Achieve both low-modulus and adhesiveness



★薄膜 (BLT 15μm) により、低熱抵抗化

Achieve low thermal resistance because of "BLT 15μm"

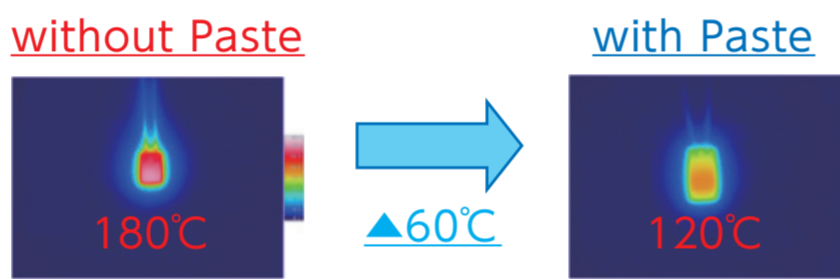


★シロキサンプリー

Low molecular siloxane free

★良好な放熱性

Good thermal conductivity



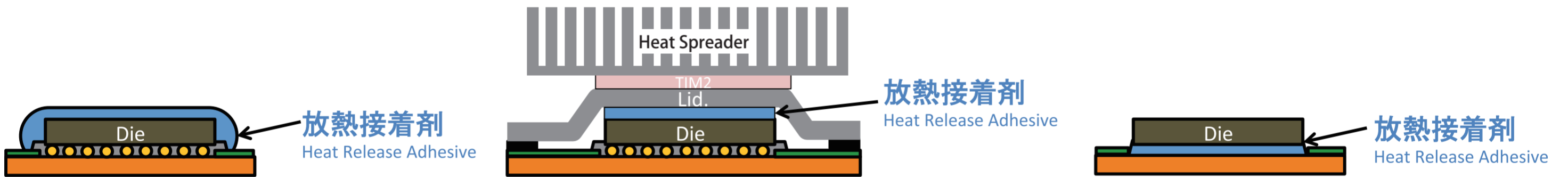
物性 Properties	Normal	Low Temp Cure
Thermal Conductivity	2.5 W/m·K	2.5 W/m·K
Viscosity	70 Pa·s	100 Pa·s
BLT	15 μm	20 μm
Curing condition	150°C 2h	85°C 30min
Hardness (Type D)	50±5	40±5
Adhesive Strength (Al/Al)	7.5 N/cm²	4.0 N/cm²
Breakdown Voltage	>20 kV/mm	>20 kV/mm

用途例 Application

チップモールド材 Chip molding

接着性のあるTIM1 Adhesive TIM1

ダイボンド材 Die-bonding paste



2液常温硬化放熱接着剤 Two-Component Room Temperature Curable Heat Release Adhesive

特徴 Features

★高靱性な接着剤

Adhesive with toughness

★シロキサンプリー

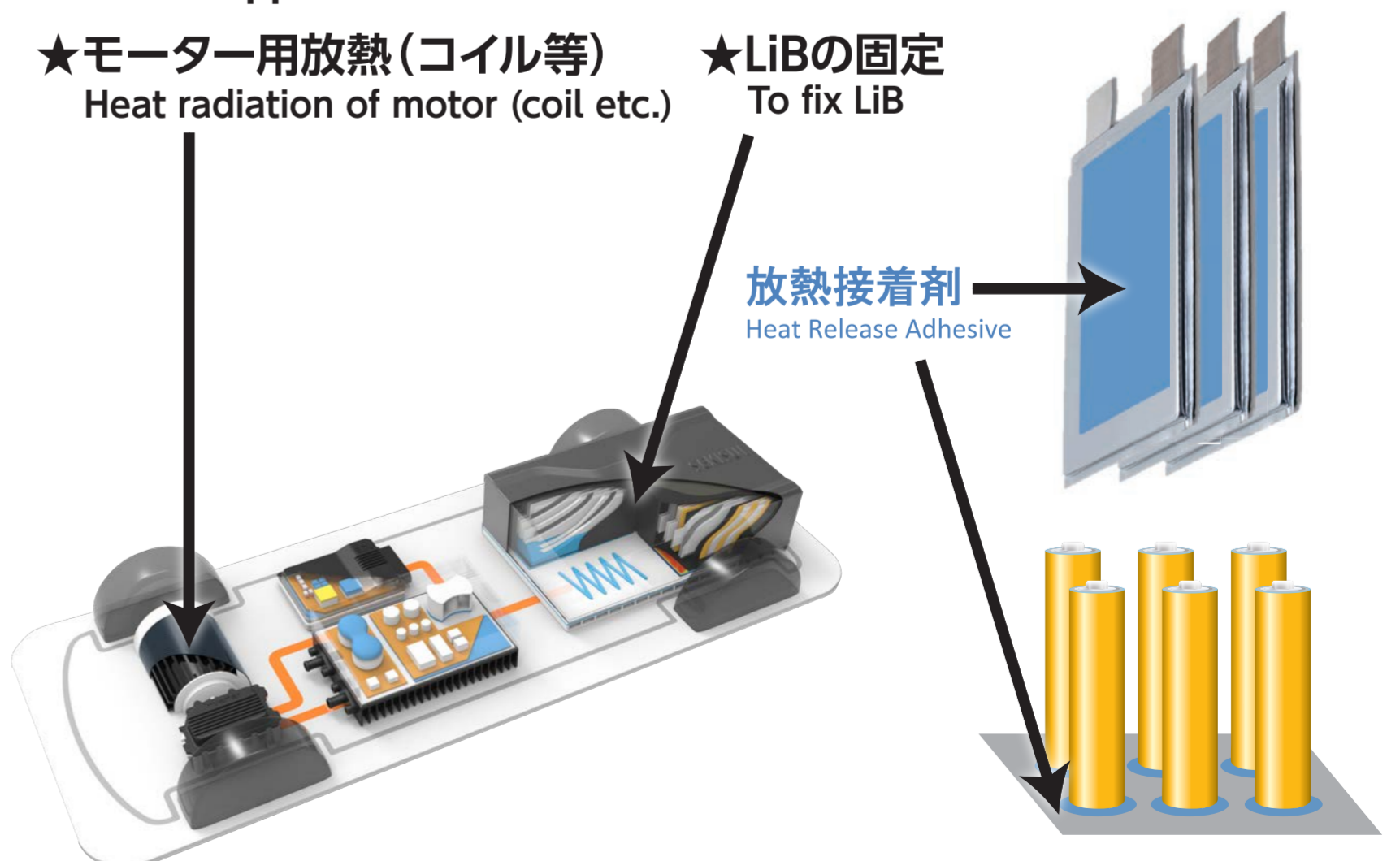
Low molecular siloxane free



用途例 Application

★モーター用放熱 (コイル等)
Heat radiation of motor (coil etc.)

★LiBの固定
To fix LiB



物性 Properties	PartA / PartB
Thermal Conductivity	2.9 W/m·K
Viscosity	A:120 Pa·s / B:80 Pa·s
Viscosity After Mixing	100 Pa·s
BLT	150 μm
Curing Condition	25°C 24h
Hardness (Type D)	60±5
Adhesive Strength (Al/Al)	9.0 N/cm²
Breakdown Voltage	≧ 20 kV/mm



問合せ先
Contact us

積水化学工業株式会社 高機能プラスチックカンパニー エレクトロニクス営業部 基板・半導体材料営業所 TEL:03-5521-0931
SEKISUI CHEMICAL CO.,LTD. High Performance Plastics Company PCB/Semiconductor Materials Sales Branch TEL:03-5521-0931